Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]

<table>
<thead>
<tr>
<th>HP Zbook 17 G2 Mobile Workstation</th>
</tr>
</thead>
</table>

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries battery and RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cords, Adapter</td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
</tbody>
</table>
Components and waste containing asbestos

Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 screw driver</td>
<td>philips #1</td>
</tr>
<tr>
<td>Description #2</td>
<td>T8</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. remove Service door
2. remove ODD module
3. remove Battery Module
4. remove KB
5. remove LOG_UP_ASSY
6. remove Clutch cover
7. remove LVDS BRK and LCD_ASSY
8. remove Speake
9. remove Thermal module
10. remove Rear cover l & r
11. remove LOG_LOW_LENS / LEFT PCB / RIGHT PCB
12. remove SMART CARD, K-lock Brk and RJ45 Brk
13. remove MXM PCB and DC-IN Cable
14. remove M/B assy
15. remove M/B RTC battery
16. divide M/B ASSY(remove BATTERY_CONN_HOLDER and RAM)
17. remove RAM module
18. remove WLAN / WWAN / SSD CARD
19. divide M/B ASSY(remove CPU_SUPP_BRK)
20. remove Power PCB Module
21. remove TP
22. remove Display assy
23. remove the bezel_sub_assy
24. remove Panel and Hinge
25. remove panel
26. remove LVDS Board and Antennas
27. remove Camera module and LVDS Cable
28. remove Mapping board, Mapping board cable
29. divide HDD assy (remove HDD module)
30. divide ODD assy (remove ODD module and ODD BEZEL and ODD BRK)
31. divide MULTIBAY HDD assy (remove HDD module and MULTIBAY PLATE and MULTIBAY PCB)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

PSG instructions for this template are available at EL-MF877-01
3.1.1 Push door latch knob to remove Service door.

3.1.2 Release screw to remove ODD module

3.1.3 Push battery knob and remove battery module, then release HDD bracket's screw and remove HDD module.
3.1.4 Remove KB

3.1.5 Remove LOG_UP_ASSY

1. Push battery knob

3. Release screw

4. Remove HDD module

1. Remove KB (release membrane and backlight FPC.)
3.1.6 Release screw and remove Clutch cover

3.1.7 Release screw and remove LVDS BRK and LCD_ASSY

PSG instructions for this template are available at EL-MF877-01
3.1.8 Release screw and remove Speaker

2. Remove speaker

3.1.9 Release cable and screw, then remove Thermal module

2. Remove LVDS BRK

3. Remove LCD ASSY

1. Release screw

1. Remove FAN’s cable

3. Remove Thermal module
3.1.10 Release screw and remove Rear cover l & r.

2. Release

2. Release screw

2. Remove Rear cover l

3. Remove Rear cover

3. Remove LEFT PCB

4. Remove RIGHT PCB

PSG instructions for this template are available at EL-MF877-01
3.1.12 Release screw and FFC, then remove SMART CARD, K-lock Brk and RJ45 Brk.

1. Release screw
2. Remove Lens
3. Remove SMART CARD
4. Remove K-Lock Brk
5. Remove RJ45 Brk

3.1.13 Release screw, then remove MXM PCB. Unplug DC-IN Cable Conn and remove DC-IN Cable.

1. Release screw
2. Remove MXM
3. Unplug DC-IN Conn.
4. Remove MDC-IN Cable

PS: Instructions for this template are available at EL-MF877-01
3.1.14 Release screw, then remove M/B

1. Release screw
2. Remove M/B

3.1.15 Unplug connector and remove M/B RTC battery

1. Unplug RCT connector
2. Remove RCT battery

PSG instructions for this template are available at EL-MF877-01
3.1.16 Remove BATTERY CONN HOLDER and RAM From Bottom side of MB

1. Release holder snap and remove the holder
2. Release the socket lock
2. Remove RAM

PSG instructions for this template are available at EL-MF877-01
PSG instructions for this template are available at EL-MF877-01
3.1.17 Remove RAM module

PSG instructions for this template are available at EL-MF877-01
3.1.18 Release screws and Remove WLAN / WWAN / SSD CARD

1. Release Wi-Fi screws
2. Remove Wi-Fi card
3. Release WWAN screws
4. Remove Wi-Fi card
5. Release SSD screws
6. Remove SSD card

PSG instructions for this template are available at EL-MF877-01
3.1.19 Remove CPU from MB

1. Release Screw lock
2. Remove CPU

PSG instructions for this template are available at EL-MF877-01
3.1.20 Remove Power, Finger print and Function PCB Module

1. Release screw

2. Remove Power PCB

1. Release screw

3. Remove FBR PCB

2. Remove FBR Brk

3. Remove FBR Bezel

2. Remove Fun PCB

1. Release the screws

PSG instructions for this template are available at EL-MF877-01
3.1.22 Remove Display assay

1. Remove screw pad

2. Release screw

3.1.23 Remove the bezel_sub_assay

1. Remove bezel sub assy
3.1.24 Release screw for Panel and Hinge

1. Remove screw

2. Remove hinge

PSG instructions for this template are available at EL-MF877-01
3.1.26 Release screw and Remove LVDS Board and Antennas

3.1.27 Remove Camera module and LVDS cable

1. Release screw

2. Remove LVDS Board

3. Remove antenna

1. Release camera module and LVDS cable
3.1.28 Remove Maping board, Maping board cable, antenna

1. Remove Maping board
2. Remove Maping board cable
3. Remove antenna
3.1.29 Release screw and remove HDD module (HDD_ASSY)
3.1.30 Release screw, ODD brk, ODD BEZEL ASSY

1. Release screw
2. Remove ODD brk
3. Remove ODD BEZEL ASSY

PSG instructions for this template are available at EL-MF877-01
3.1.31 Release screw and remove ODD brk (Multibay_assy)

1. Release screw

2. Remove ODD brk
3.1.31 Release screw and remove HDD module

1. Release screw
2. Remove HDD module

3.1.31 Release screw, remove Multibay_HDD_plate and PCB
1. Release screw

2. Remove Multibay HDD plate

3. Remove Multibay HDD PCB